LINTEC Corporation

Presentation Materials on Company Information

LINTEC Corporation

TSE Prime | 7966

Nov. 9, 2026

LSV 2030
LINTEC SUSTAINABILITY VISION
Stage 2

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01

About LINTEC

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LINTEC Corporation

Company overview

Name	LINTEC Corporation
Head Office	Itabashi-ku, Tokyo, Japan
Securities Code	7966 (Tokyo Stock Exchange, Prime Market)
Established	October 15, 1934
Common Stock	23.3 billion yen (as of March 31, 2026)
Number of Employees	Consolidated: 5,237 (as of March 31, 2026)
Net Sales	Consolidated: 319.4 billion yen (year ended March 31, 2026)
Lines of Business	Development, manufacture, and sale of adhesive products, adhesive-related equipment, specialty papers, release papers and films, and other products
Business Bases	Domestic consolidated subsidiaries: three companies Overseas consolidated subsidiaries: 37 companies

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History 1



1927 Gummed tape manufacturer FUJI SHIKO CORPORATION established (Itabashi, Tokyo)

1934 FUJI SHOKAI established; begins production and sale of gummed tape for packaging.



1960 Start of production and sale of adhesive papers and films for label use

Adhesive business expanded to applications in industrial fields such as motorcycles, automobiles, and exterior decoration.

1984 Company renamed FSK CORPORATION

1986 Development of UV curable dicing tape and full-scale entry into semiconductor-related fields



1987 MADICO, INC. (US) acquired



1990 Merger with SHIKOKU PAPER CO., LTD. and SOHKEN KAKO CO., LTD.; Company renamed LINTEC Corporation

Business expanded to the fields of specialty papers, release papers and films, adhesive papers and films, and related equipment.

1991 Full-scale entry into optical display-related fields



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History 2

1994 — PT. LINTEC INDONESIA established

2000 — LINTEC INDUSTRIES (MALAYSIA) SDN. BHD. established

2002 — LINTEC (SUZHOU) TECH CORPORATION established



2004 — LINTEC KOREA, INC. established

2011 — LINTEC (THAILAND) CO., LTD. established



2013 — Nano-Science & Technology Center opened (US)

2015 — Advanced Technology Building constructed at Research Center



2016 — MACTAC AMERICAS, LLC acquired



2021 — DURAMARK PRODUCTS, INC. (US) acquired

Later merged with a subsidiary of MACTAC AMERICAS, LLC

2022 — SPINNAKER PRESSURE SENSITIVE PRODUCTS LLC (US) established by transfer of operations from a manufacturer within same industry

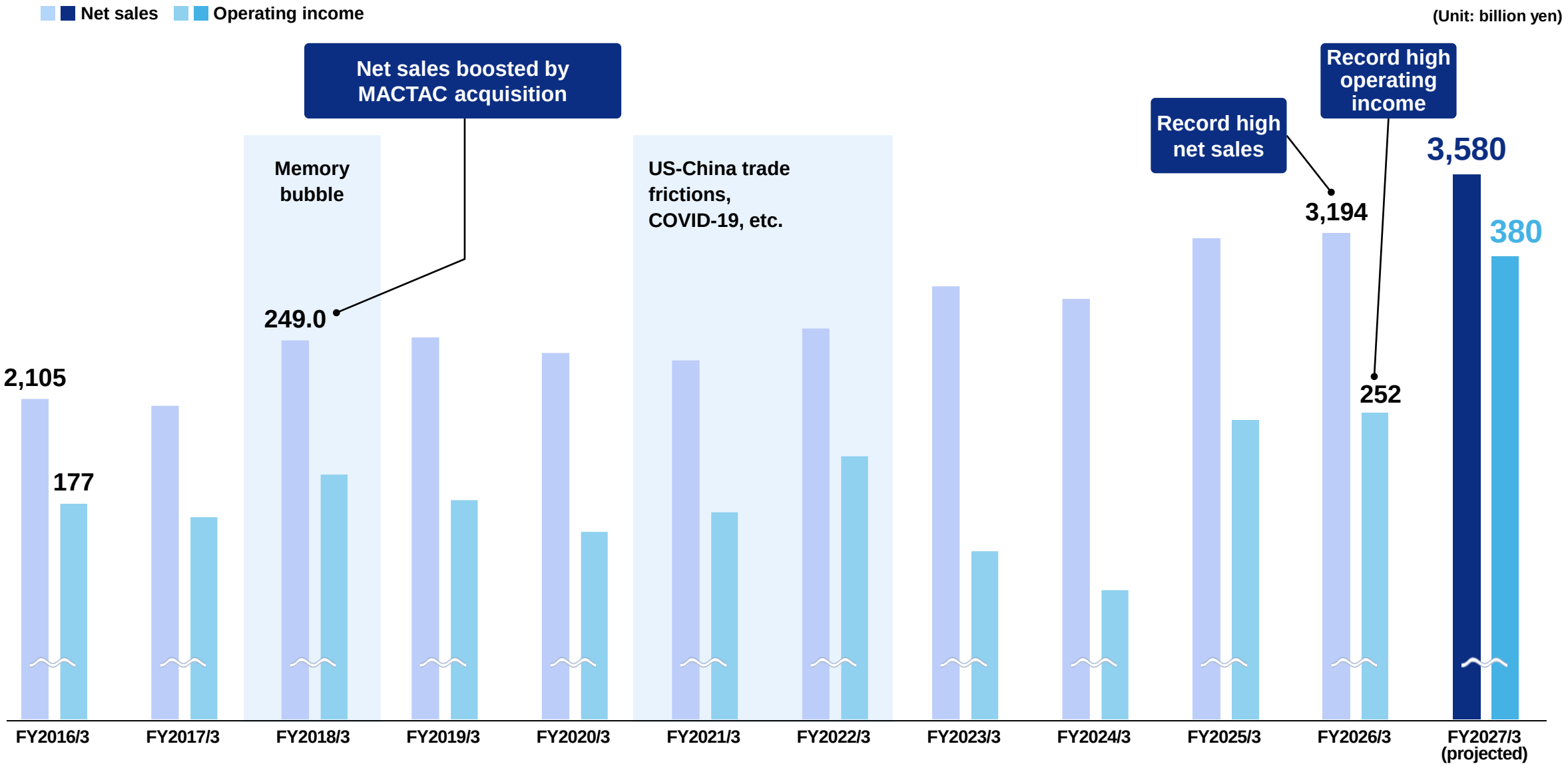
Later merged with a subsidiary of MACTAC AMERICAS, LLC

2023 — Business of LABEL SUPPLY (CANADA) acquired

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Financial performance trends / Net sales, operating income

LINTEC Corporation

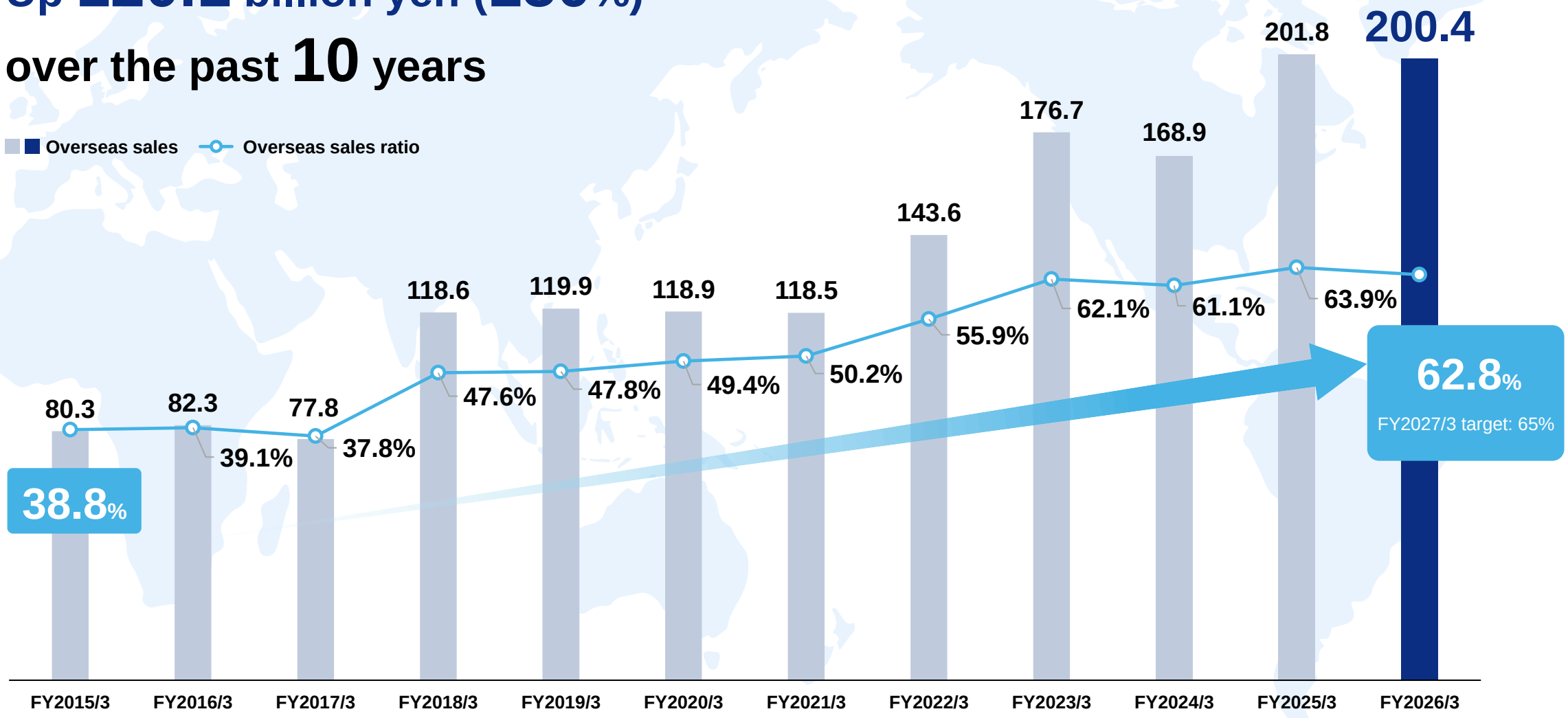


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LINTEC Corporation

Up 120.1 billion yen (150%) over the past 10 years

(Unit: billion yen)

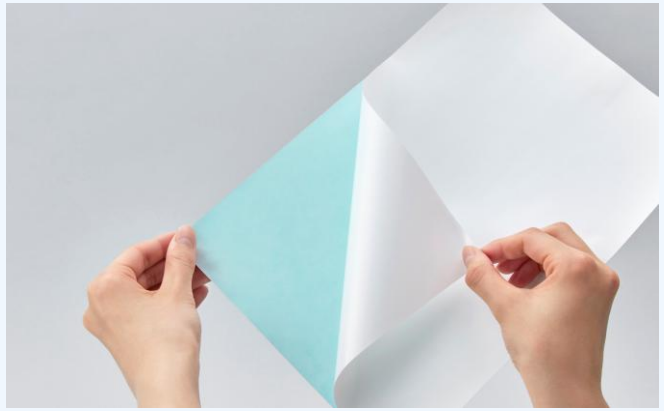


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Basic structure of adhesive products



Achieved entirely using in-house technologies



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Integrated production structure for adhesive products

- **LINTEC's integrated production structure for adhesive products addresses processes ranging from the production of the base paper for release paper to the development and coating of paper and film release agents, development and coating of adhesives, and facestock improvement processing.**
- **We also developed and produce related equipment that fully draws out the special characteristics of the adhesive products, which made it possible for us to provide comprehensive solutions using our materials and equipment.**

Materials

- **Base paper for release paper**

Paper



Papermaking

- **Release paper, release film**

Surface improvement agent layer



Facestock (paper, film)

Surface improvement agent development and coating

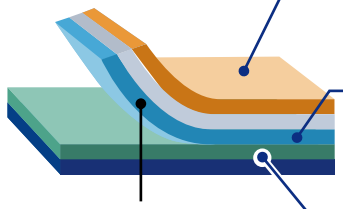
Release agent layer



Release base material (paper, film)

Release agent development and coating

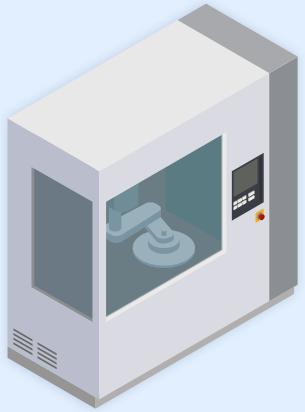
- **Adhesive paper, adhesive film**



Adhesive agent development and coating, lamination

Equipment

Semiconductor-related equipment, labeling machines



Providing comprehensive solutions using our materials and equipment

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Four core technologies

1

Adhesive applications

Expanding domains of application of the basic features of adhesive products (i.e., adhesion and release) by developing adhesive agents, base materials, and related compound technologies

2

Surface improvement

Improving performance and adding new features via chemical and physical treatment of paper and film surfaces

3

System development

Proposing advanced solutions by developing high-performance systems, including machinery and equipment systems, that harness the distinguishing features of materials

4

Specialty paper and release materials production

Drawing on proprietary papermaking and coating, impregnation, and lamination technologies to develop functional papers and high value-added materials above and beyond traditional conceptions of paper

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Three business segments built on our core technologies

Core technologies

1. Adhesive applications
2. Surface improvement
3. System development
4. Specialty paper and release materials production

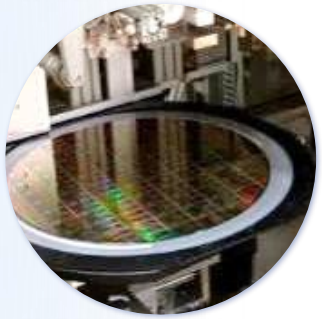
Printing and Industrial Materials Products

- Printing & Variable Information Products Operations
- Industrial & Material Operations



Electronic and Optical Products

- Advanced Materials Operations
- Optical Products Operations



Paper and Converted Products

- Fine & Specialty Paper Products Operations
- Converted Products Operations



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02

Business segments

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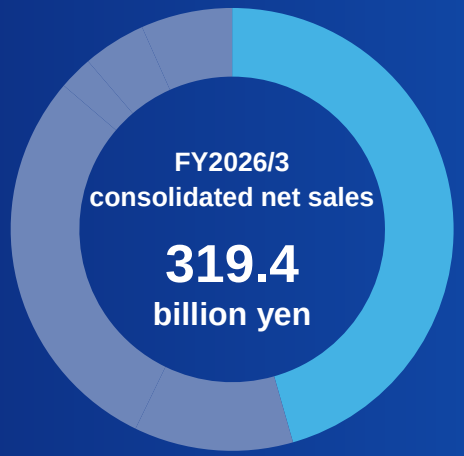
Printing and Industrial Materials Products

Printing & Variable Information Products Operations

Sales in this business operation

145.5 billion yen

45.6%



Adhesive papers and films for label use

- Main types: permanent, removable, re-applicable
- Properties: printability, durability, heat resistance, water resistance, cold resistance, curved-surface adhesion, dimensional stability, design potential, and others

Commercial flow



LINTEC



Seal and label printing and processing companies



End users







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Printing & Variable Information Products Operations

■ Specific applications of adhesive papers and films for label use / key required performance

Mainly using adhesive papers

Food and beverages



- Water resistance
- Curved-surface adhesion
- Cold resistance, etc.

Logistics and mail order



- Printability
- Stampability
- Cold resistance, etc.

Mainly using adhesive films

Everyday items



- Water resistance
- Curved-surface adhesion
- Design potential, etc.

Automotive



- Oil- and water-resistance
- Durability
- Heat resistance, etc.

Medical, pharmaceutical



- Printability
- Chemical resistance
- Tamper-evident, etc.

Home appliances



- Durability
- Heat resistance
- Gas permeability, etc.

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■ MACTAC AMERICAS, LLC

- In December 2016, we acquired MACTAC AMERICAS, the third largest manufacturer of adhesive products for labels in North America, for approximately 34.0 billion yen, thereby marking full-scale entry to the North American market.
- This included approximately 30.0 billion yen in goodwill (amortized over 10 years).
- MACTAC AMERICAS acquired competitor DURAMARK PRODUCTS, INC. in April 2021 for approximately 6.5 billion yen to expand production capacity.
- In February 2022, MACTAC AMERICAS acquired the business of a competitor for approximately 4.5 billion yen to grow its business territory, establishing SPINNAKER PRESSURE SENSITIVE PRODUCTS LLC.
- In May 2023, to grow its sales network in Canada, MACTAC AMERICAS acquired the business of competitor LABEL SUPPLY for approximately 7.0 billion yen.



◄ Has hot-melt adhesive technology, which helps to lessen environmental impact

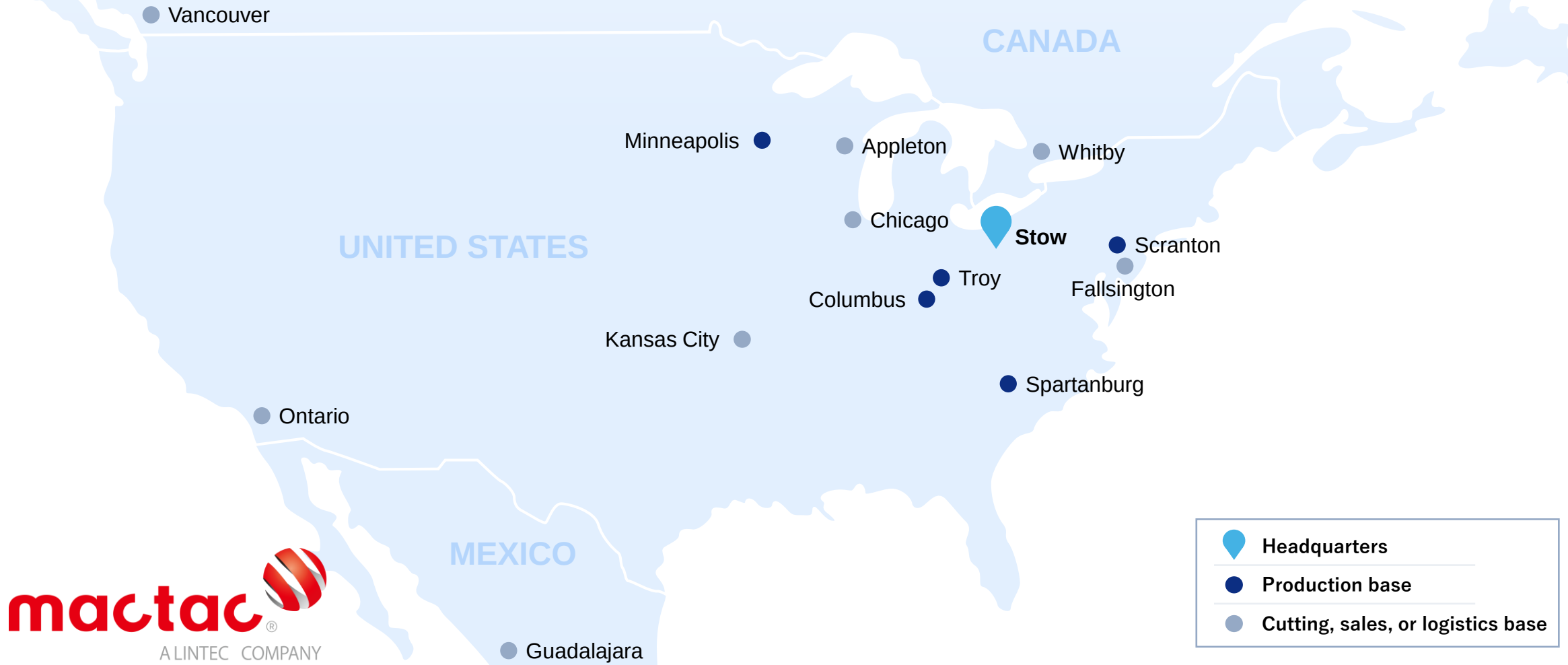
Established	1959
Location	Ohio, US
Number of Employees	1,018 (as of March 31, 2025)
Lines of Business	Manufacture and sale of label materials for printing, variable information label materials, graphic sheets, industrial tape, medical tape, and other products



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The MACTAC Group covering the entire North American market

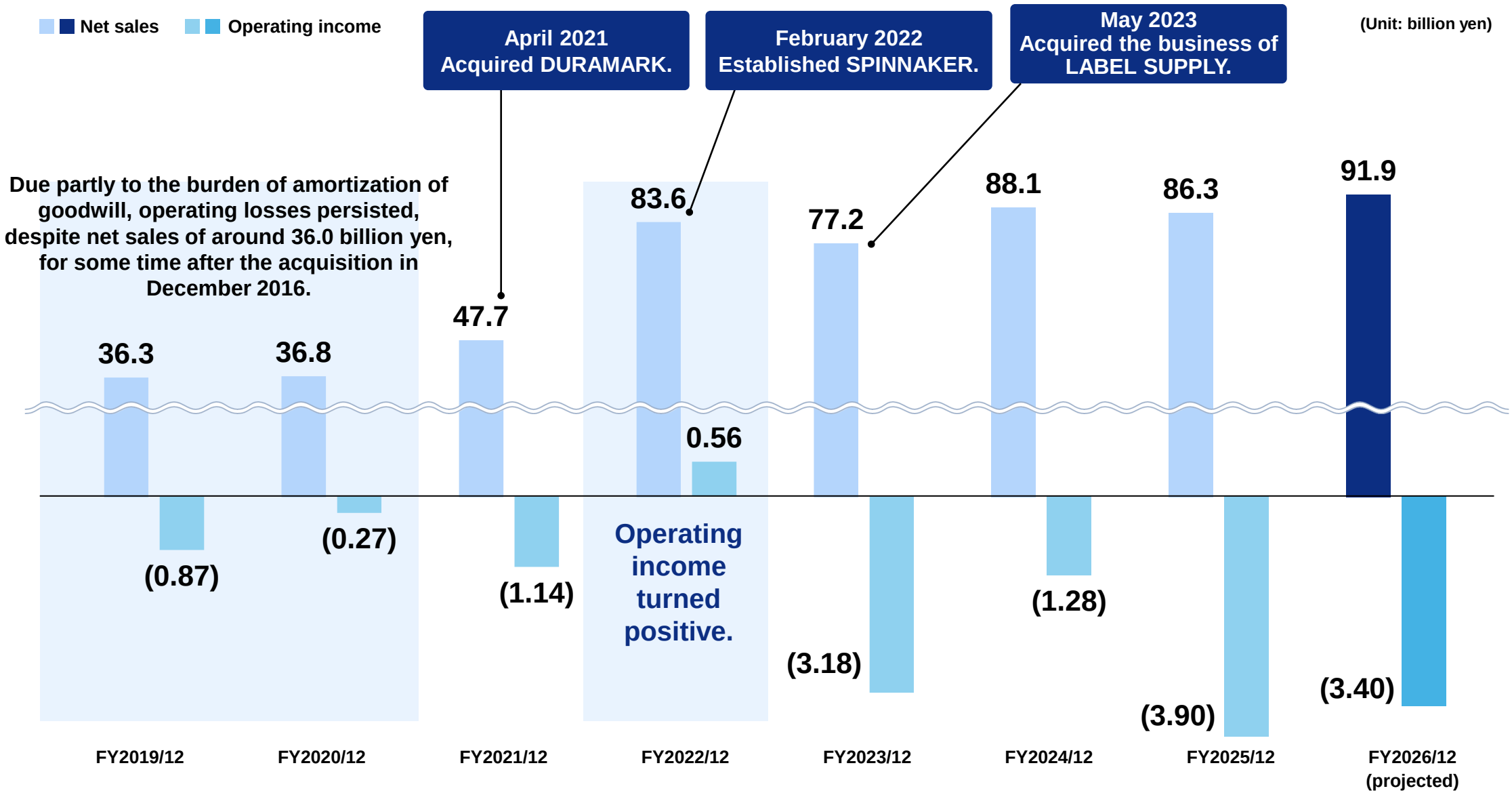
- **MACTAC AMERICAS, LLC, the US subsidiary, has undertaken a succession of acquisitions since 2020.**
- **It has established a solid position in the growing North American label market by expanding its production capacity, business foundations, and the like.**



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MACTAC Group financial performance trends



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Printing and Industrial Materials Products

Industrial & Material Operations

Sales in this business operation

37.1 billion yen

11.6%



Window films (for buildings, automobiles)

Signage, advertising, and interior finishing mounting films

Automotive-use adhesive products

Industrial-use adhesive tapes

Labeling machines, barcode printers

etc.



Window film for buildings



Window film for automobiles



Signage, advertising, and interior finishing mounting film

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Industrial & Material Operations

Main products and properties of Industrial & Material Operations

Window film for buildings



- Glass shatterproofing
- Solar control
- Cutting UV rays
- Security, etc.

Window film for automobiles



- Glass shatterproofing
- Solar control
- Cutting UV rays, etc.

Signage, advertising, and interior finishing mounting films



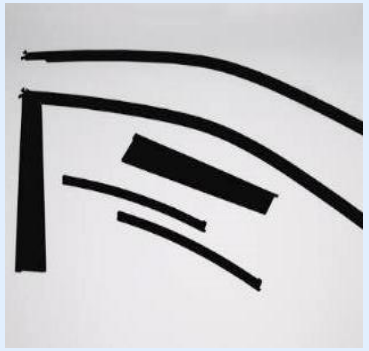
- Weather resistance
- Ease of installation
- Wide variety, etc.

Protective film for aluminum wheels



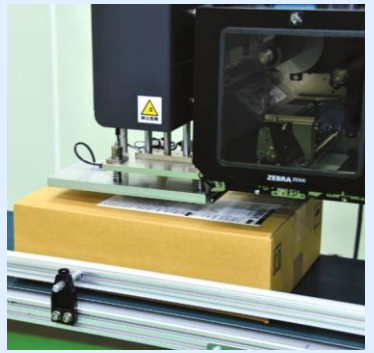
- Weather resistance
- Removability, etc.

Paint replacement films for door sashes



- Weather resistance
- Ease of installation, etc.

Labeling machines



- High speed, high efficiency
- Usability
- Automation, etc.

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MADICO, INC., VDI, LLC

MADICO, INC.

- Acquired by the LINTEC Group in 1987
- Has strong brand power and an extensive sales network, centered on North America, in building and automotive window films, with an approximately 10% share of the North American market.
- Amid recent growth in demand for security film, its film products are used in public facilities in five US states.

Established	1903
Location	Florida, US
Number of Employees	192 (as of March 31, 2025)
Net Sales	11.0 billion yen (FY2024/12)
Lines of Business	Manufacture and sale of window films, special function films, and other products



VDI, LLC

- Acquired by the LINTEC Group in 2016
- A functional film manufacturer with metallizing technologies for forming thin metal layers on film surfaces.
- Sales of sputtering films for aerospace applications have grown sharply in recent years.

Established	1971
Location	Kentucky, US
Number of Employees	31 (as of March 31, 2025)
Lines of Business	**Manufacture and sale of metallized films, sputtering films, and other products** Sputtering: Application of high energy to metals, oxides, and other materials in a vacuum, to form particles and adhere them to film and other surfaces



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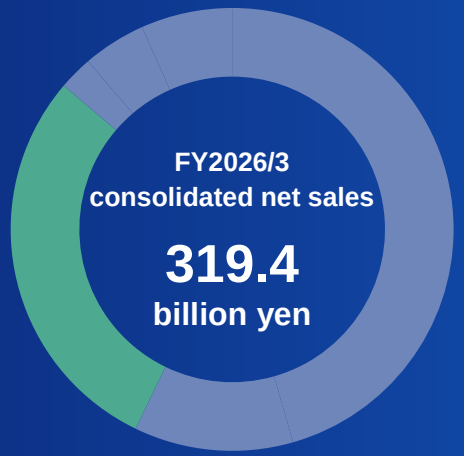
Electronic and Optical Products

Advanced Materials Operations

Sales in this business operation

92.8 billion yen

29.0%



Semiconductor-related adhesive tapes

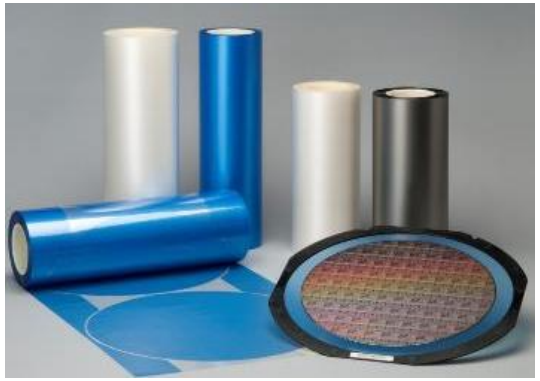
- Back grinding tapes
- Dicing tapes
- Backside coating tapes
- Dicing die bonding tapes

Semiconductor-related equipment

- Wafer mounters
- Tape laminators and removers
- UV irradiation system

Multilayer ceramic capacitor-related tapes

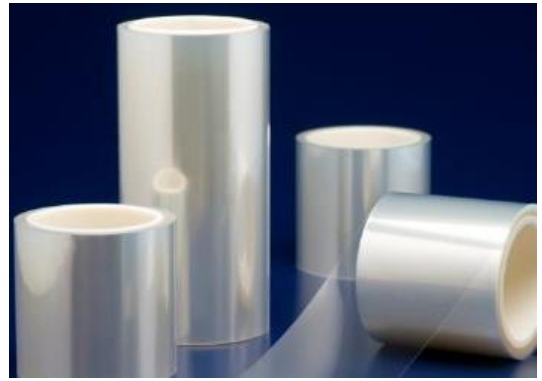
etc.



Semiconductor-related adhesive tapes



Semiconductor-related equipment



Multilayer ceramic capacitor-related tapes

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Advanced Materials Operations

■ Semiconductor manufacturing process

: Use of our tape and equipment

Front-end process



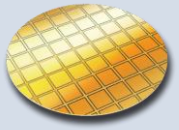
Single-crystal silicon ingot



Slicing

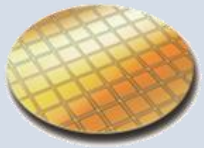


Wafer

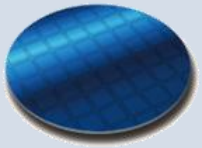


Wafer following circuit formation

Back-end process



Wafer following circuit formation

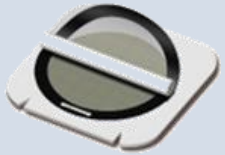


Affixing surface protective tape

Flipping



Backside grinding (thinning)

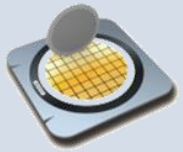


Affixing dicing tape

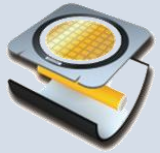
Flipping



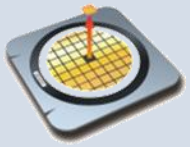
Removing surface protective tape



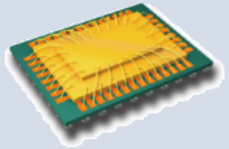
Dicing (cutting wafer)



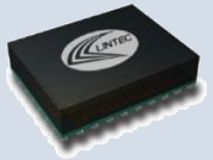
UV irradiation to tape



Pickup



Implementation, lamination



Resin sealing

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■ Semiconductor-related adhesive tapes / Main products

Backside coating tape for flip chip

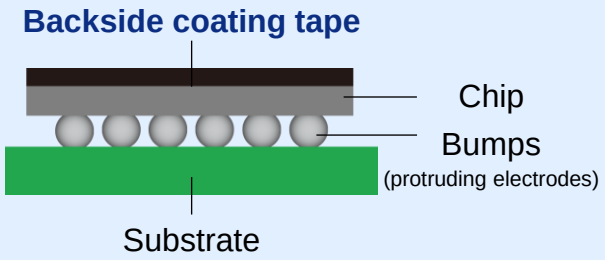
- **Tape used to protect and reinforce the backside of the chip that has bumps (electrodes) on the circuit surface and is mounted on the substrate using flip-chip technology.**

Key properties

- **Reduces transmission of light to and lessens negative effects on circuit surface.**
- **Differs from liquid mold coatings in uniformity of thickness and simplified work processes.**
- **Since it can be affixed in relatively low temperatures, thermal damage to circuitry can be reduced. Use with our affixing equipment helps develop more reliable production lines.**
- **Our product lineup includes tape combined with dicing tape and tape that permits transmission of infrared rays.**



▼ **Flip-chip installation**



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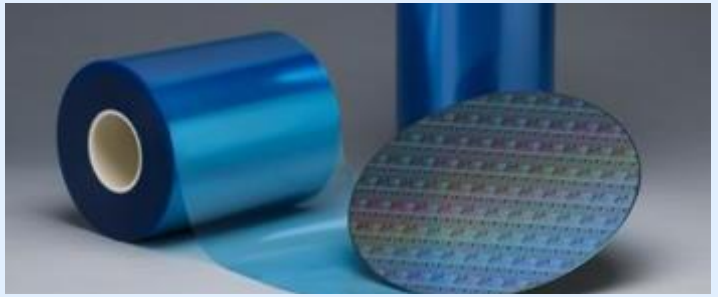
■ Semiconductor-related adhesive tapes / Main products

Wafer surface protective tape for use in SDBG

- **Tape used to protect the circuit surface in grinding of the backside of wafers in the SDBG process***

  * Stealth dicing before grinding is a processing technology that uses lasers to form cracks inside the wafer before grinding its backside. It allows more chips to be taken from a single wafer than the conventional process using blades and produces high-strength chips.

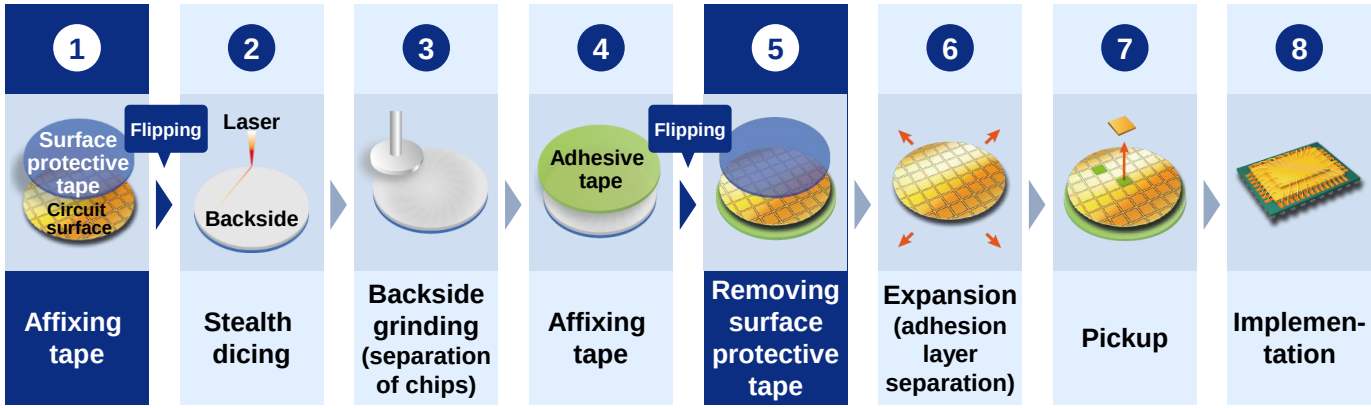
  * Stealth dicing is a laser dicing technology developed by Hamamatsu Photonics K.K.



Key properties

- **High adhesive power prevents chip scattering and flooding by grinding water.**
- **Reduces chip damage during backside grinding.**
- **Can be used to produce chips as thin as 30 μm or less.**

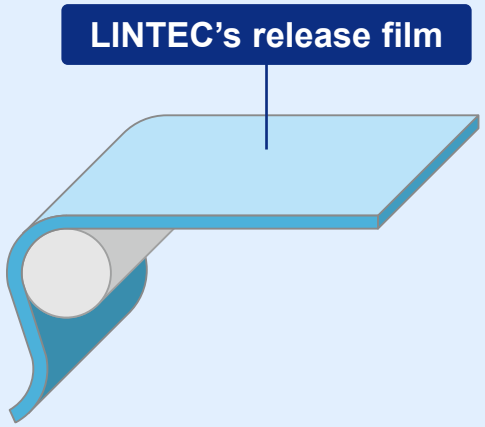
▼ Semiconductor production process using SDBG



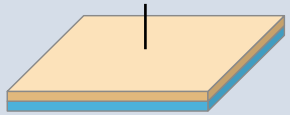
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■ Multilayer ceramic capacitor-related tapes

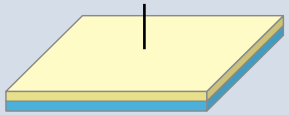
Multilayer ceramic capacitor production process







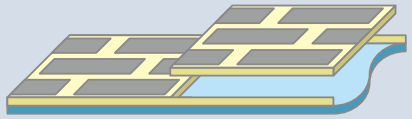
Coating



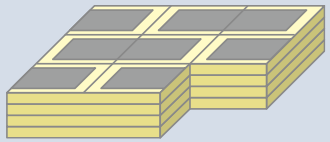
Heat drying



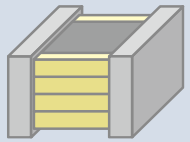
Internal electrode printing



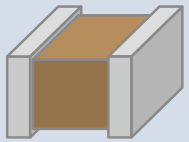
Cutting, release



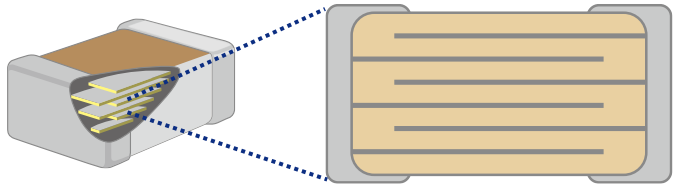
Lamination, pressure bonding, cutting



Calcination, external electrode formation



Plating



Forming hundreds of layers in one square mm or less.

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Electronic and Optical Products

Optical Products Operations

Sales in this business operation

7.9 billion yen

2.5%



Optical display-related adhesive products

Touch screen-related products



Using a touch screen



Optical display-related adhesive products



Optical display-related adhesive products

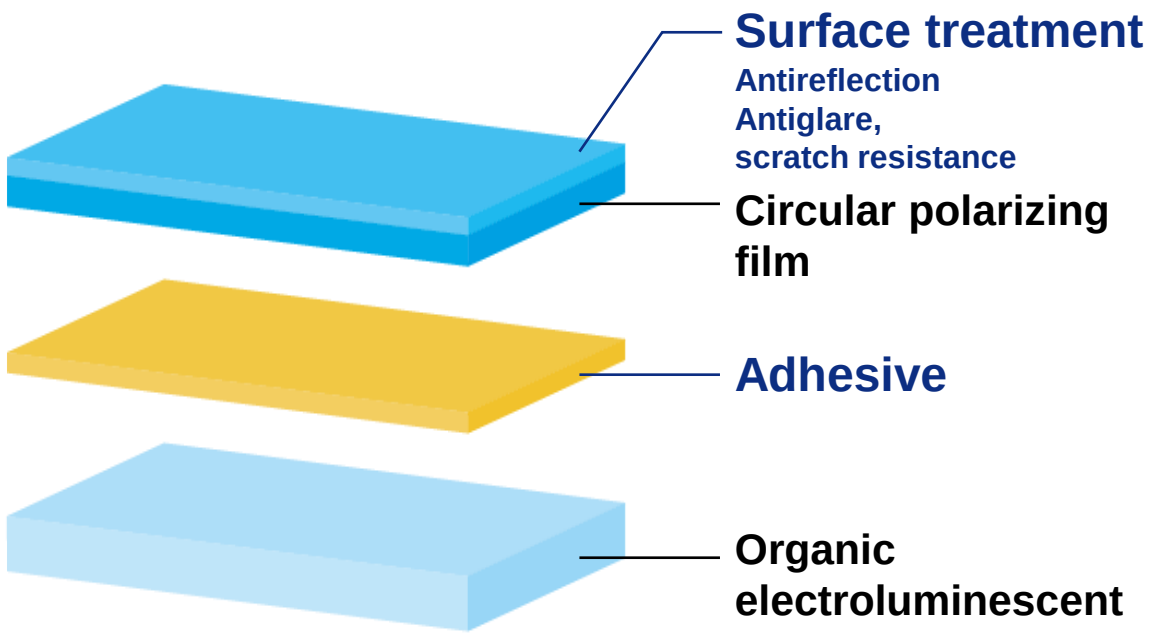
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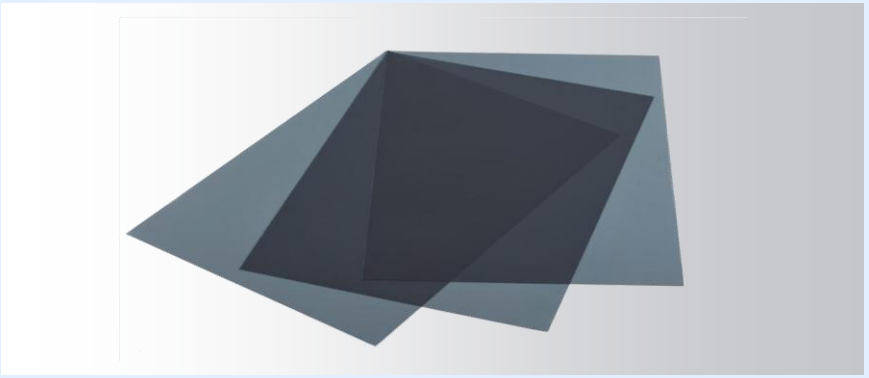
Optical Products Operations

■ Optical display-related adhesive products

Adhesive products for optically functional films essential to displaying images on OLED displays, including those used in smartphones, tablets, and large-screen TVs

▼ OLED display structure







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Optical Products Operations

■ Touch screen-related products / Main products

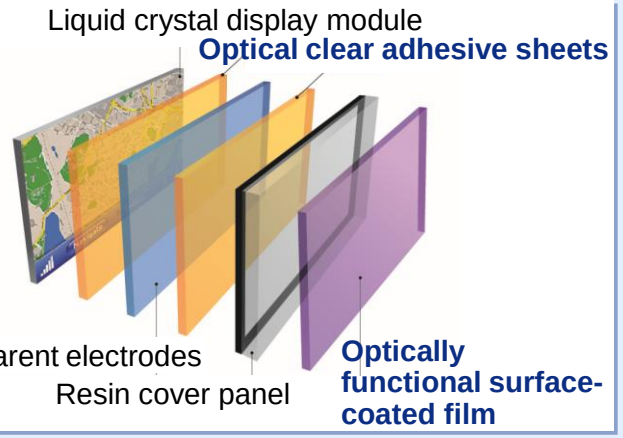
Onboard optical clear adhesive sheets

- **High-performance optical double-sided adhesive sheets used on onboard touch screens**

Key properties

- **Satisfy strict durability standards essential to onboard use**
- **Suppress outgassing from plastic materials.**

▼ Onboard touch screen structure



Light diffusion films

- **Optically functional film that efficiently and optimally diffuses incident light in the necessary directions**
- **Realize brighter screen displays on reflective displays without backlights.**

▼ Examples of use of light diffusion films



Smartwatch



GPS navigation for bicycle

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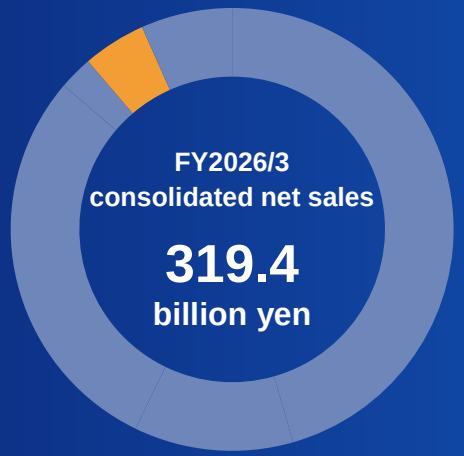
Paper and Converted Products

Fine & Specialty Paper Products Operations

Sales in this business operation

14.7 billion yen

4.6%



- Color papers for envelopes
- Colored construction papers
- Special function papers (oil- and water-resistant papers, dust-free papers, etc.)
- High-grade printing papers
- Construction material papers

etc.



Color papers for envelopes



Colored construction papers



Oil- and water-resistant papers

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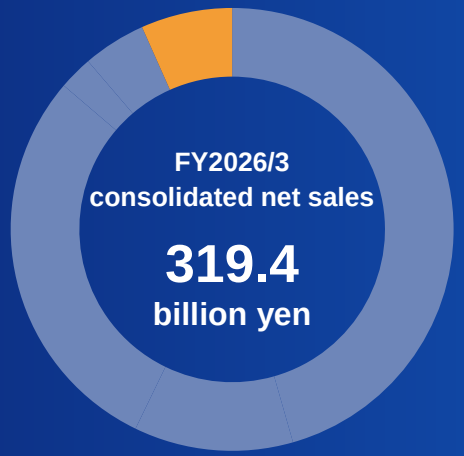
Paper and Converted Products

Converted Products Operations

Sales in this business operation

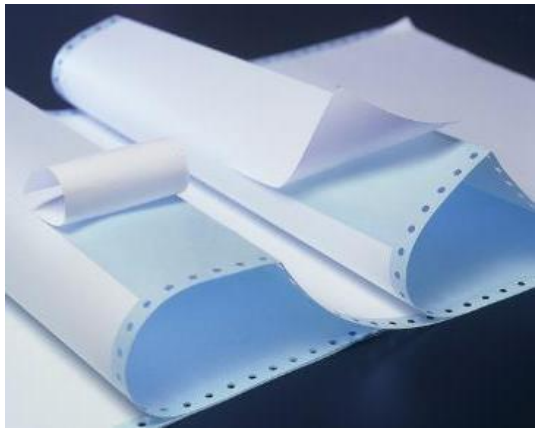
21.3 billion yen

6.7%



- Release papers for adhesive products
- Release papers for electronic materials
- Release films for optical-related products
- Casting papers for synthetic leather
- Casting papers for carbon fiber composite materials

etc.



Release papers for adhesive products



Casting papers for synthetic leather



Casting papers for carbon fiber composite materials

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03

Consolidated financial results

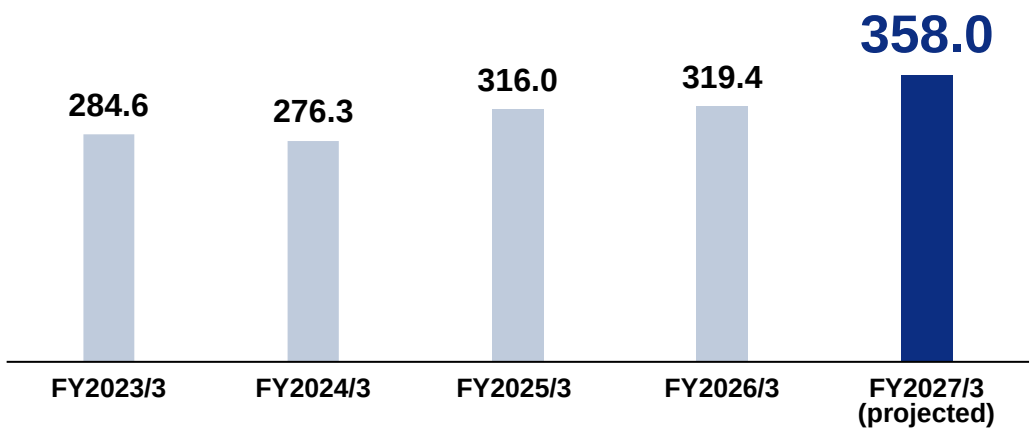
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Trends in full-year consolidated financial results

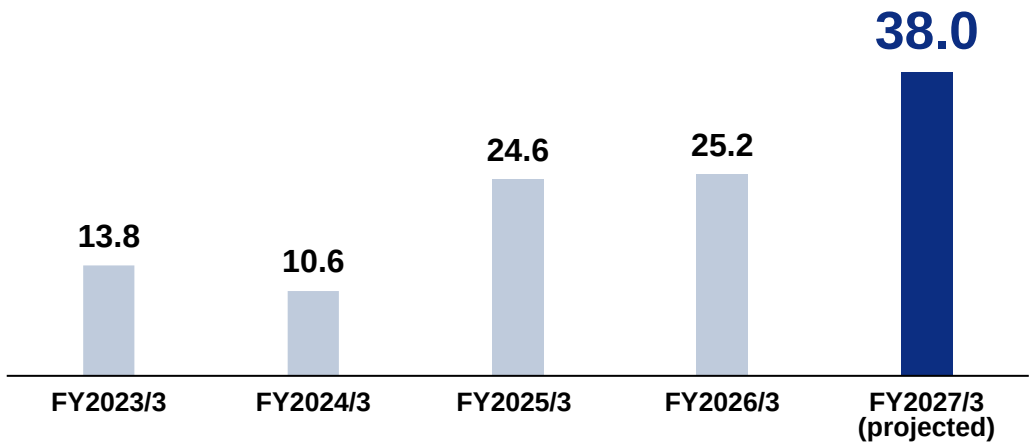
LINTEC Corporation

(Unit: billion yen)

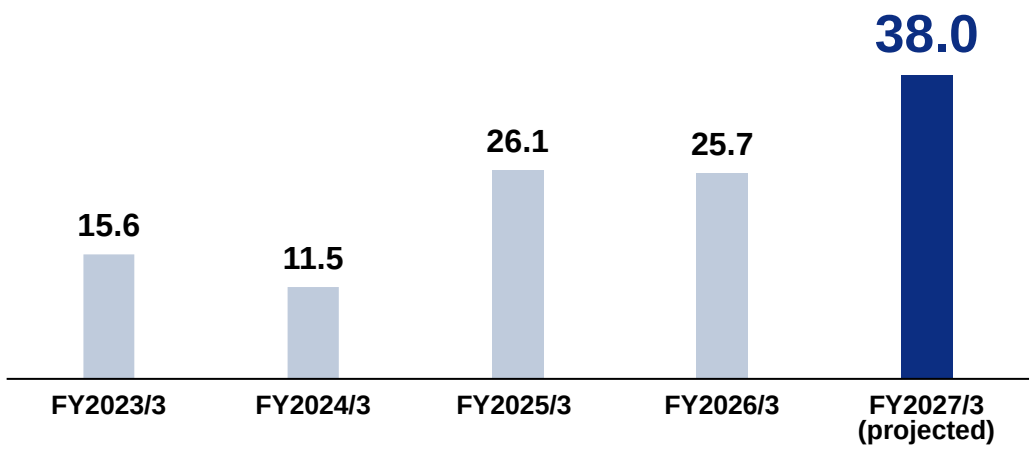
Net sales



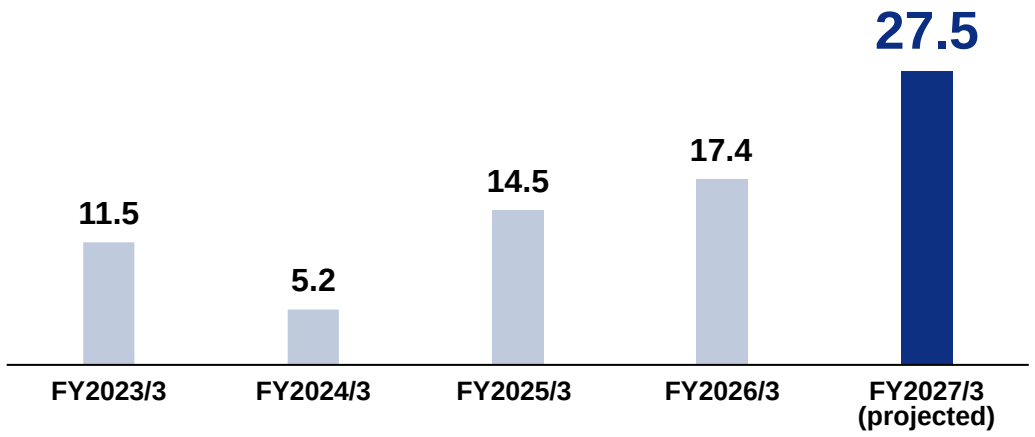
Operating income



Ordinary income



Profit attributable to owners of parent

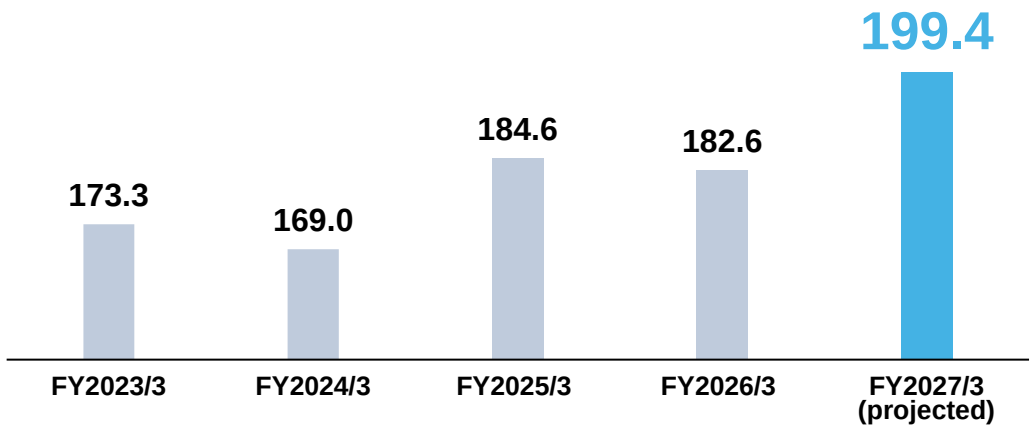


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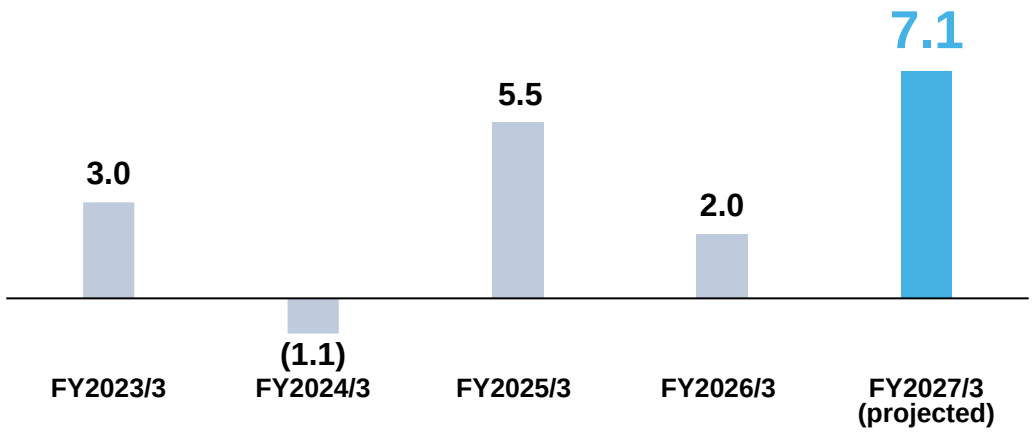
Printing and Industrial Materials Products

(Unit: billion yen)

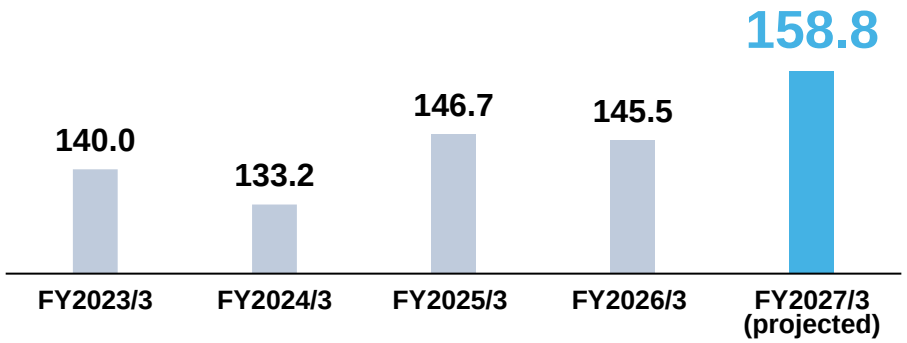
Segment net sales



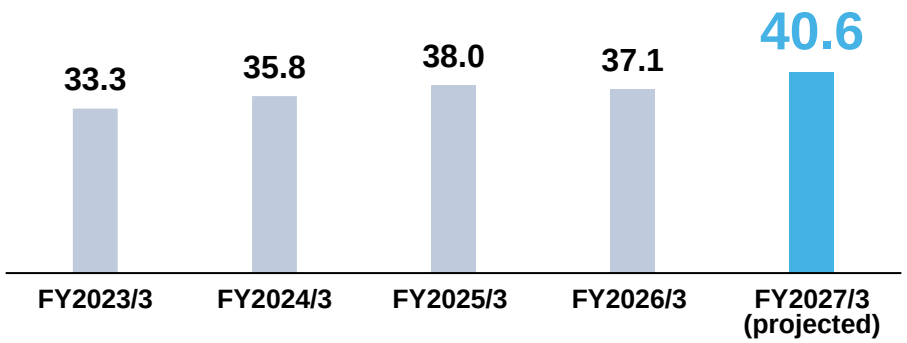
Segment operating income



Printing & Variable Information Products Operations sales



Industrial & Material Operations sales

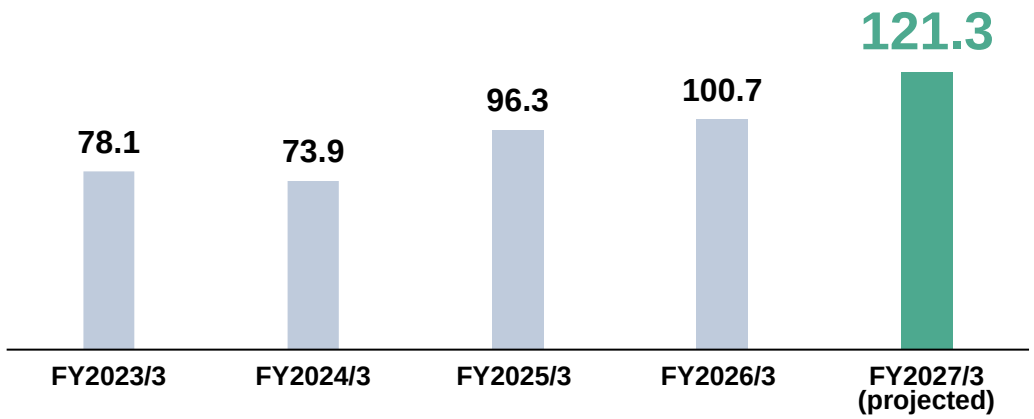


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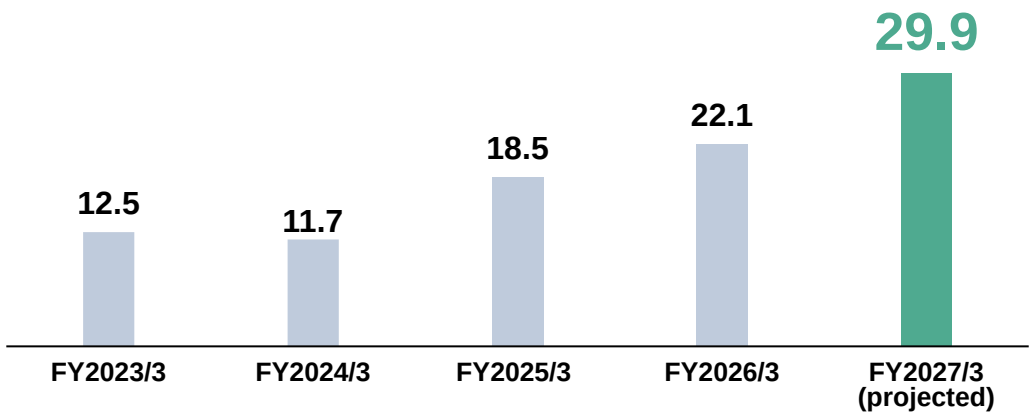
Electronic and Optical Products

(Unit: billion yen)

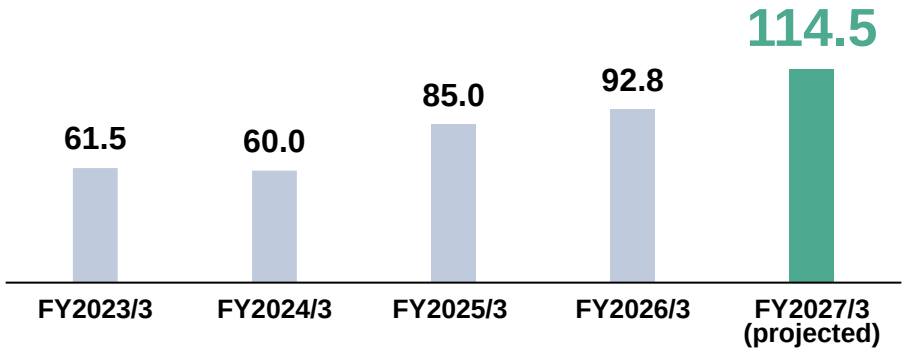
Segment net sales



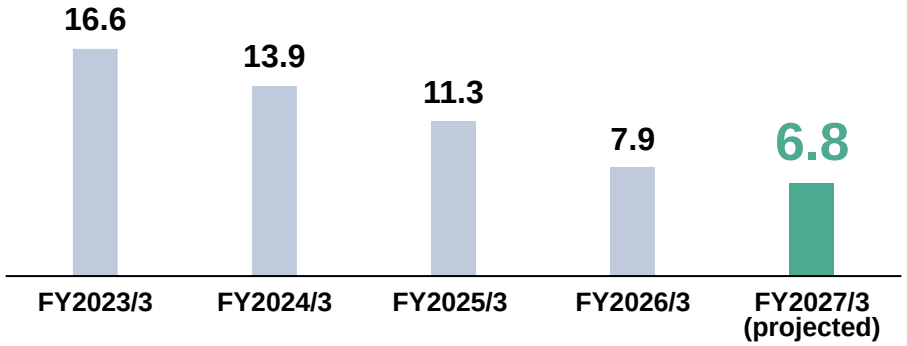
Segment operating income



Advanced Materials Operations sales



Optical Products Operations sales

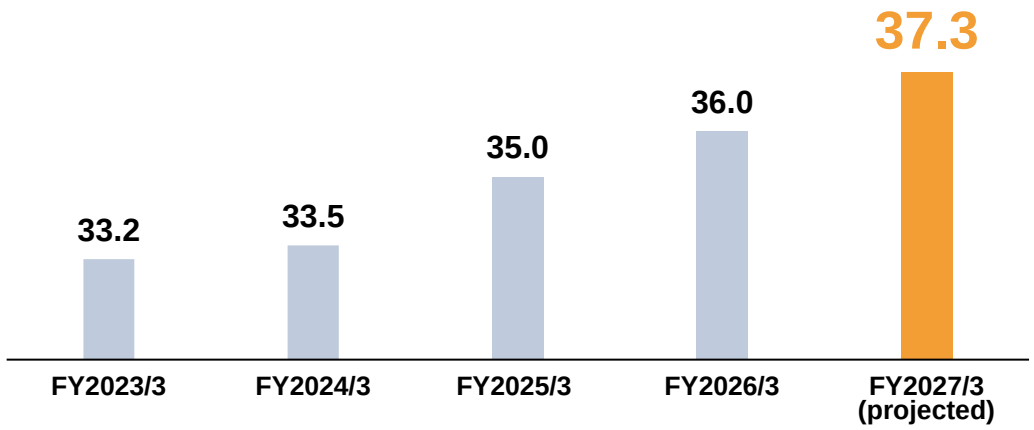


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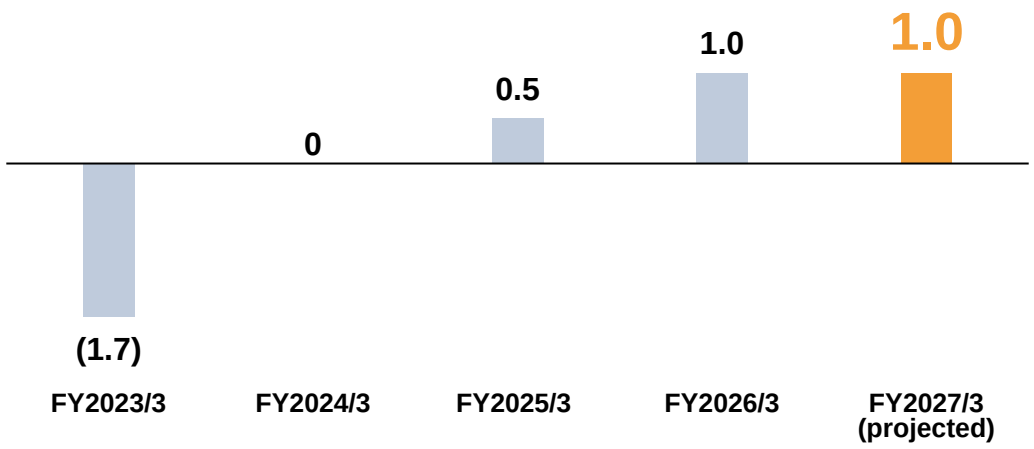
Paper and Converted Products

(Unit: billion yen)

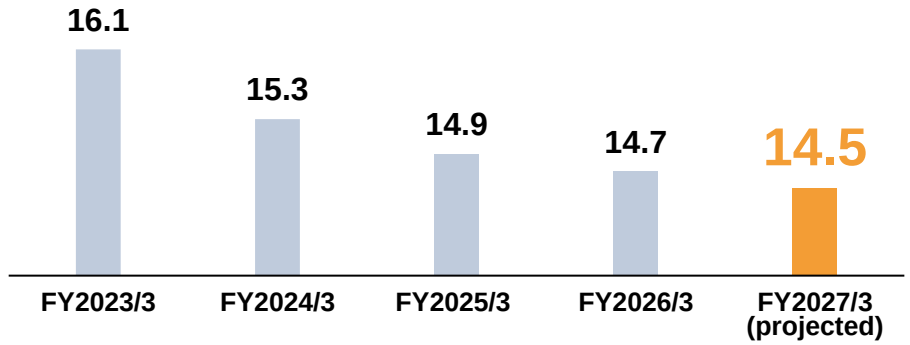
Segment net sales



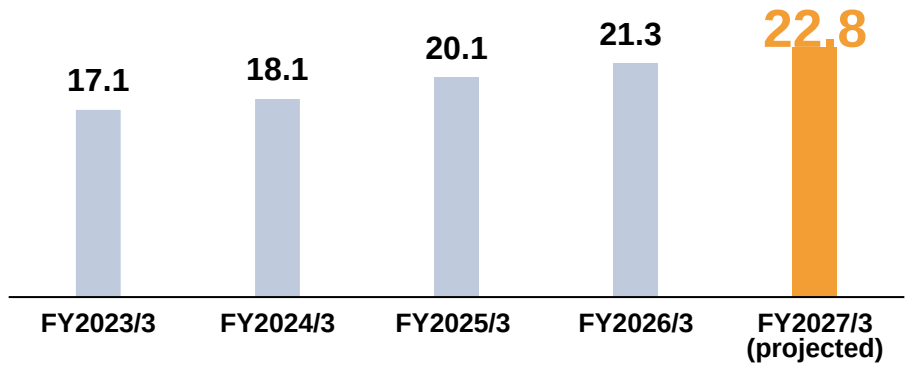
Segment operating income



Fine & Specialty Paper Products Operations sales



Converted Products Operations sales



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04

Shareholder returns

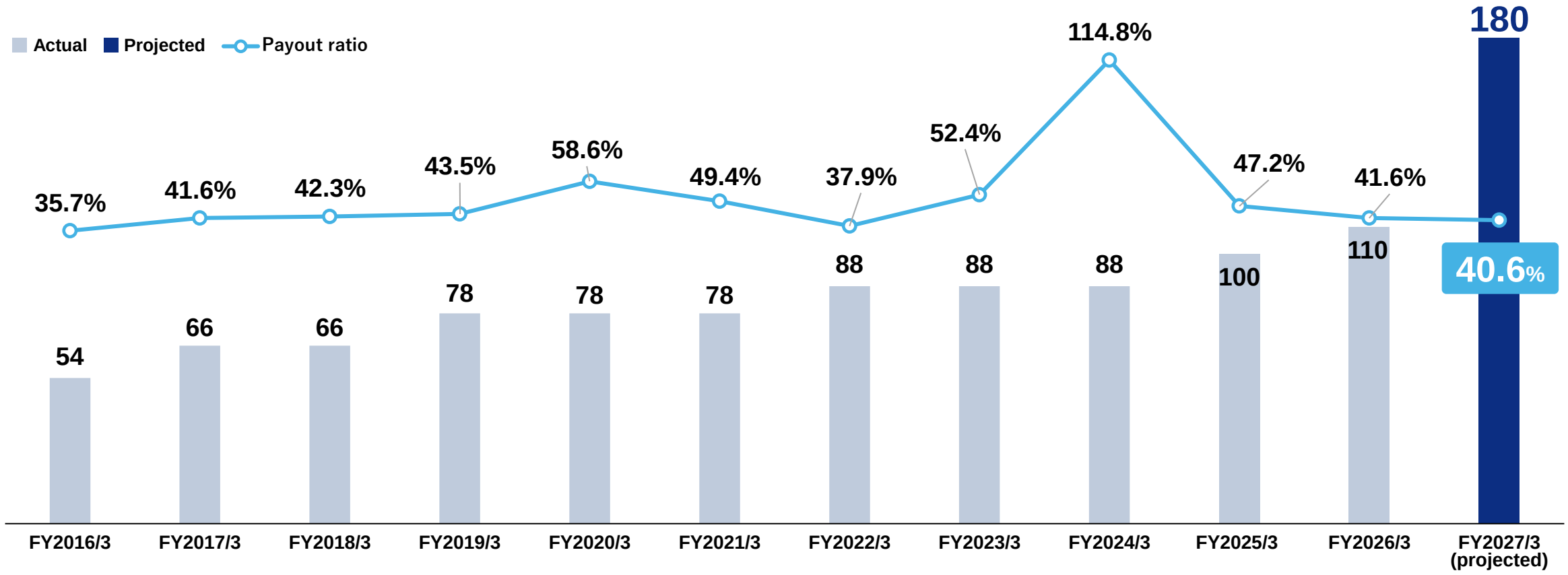
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Trends in dividends/share

(Unit: yen)

Dividend policy changed in FY2024/3

- In principle, no decrease in dividends over the four years through FY2027/3, the final fiscal year of the LSV 2030-Stage 2 Medium-term Business Plan
- Dividend payments that target a payout ratio of 40% or higher or DOE (dividend on equity ratio) of 3%



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05

Long-term Vision, Medium-term Business Plan

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Long-term Vision

Title	LINTEC SUSTAINABILITY VISION 2030 (LSV 2030)
Period	April 2021-March 2030
Basic Policy	Contribute to realizing a sustainable world by strengthening the corporate structure through innovation and creating new products and businesses for sustainable growth
Key Initiatives	1. Solve social issues. 2. Foster innovation to build a robust corporate structure. 3. Create new products and businesses to deliver sustainable growth.

2021

2030

FY2030/3 financial indicators

Operating profit margin
12% or more

Return on equity (ROE)
10% or more

LSV 2030
LINTEC SUSTAINABILITY VISION

LSV 2030-Stage 1 Medium-term Business Plan | LSV 2030-Stage 2 Medium-term Business Plan | LSV 2030-Stage 3 Medium-term Business Plan

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■ Management targets for FY2027/3, the final fiscal year of Stage 2

Period April 2024-March 2027

(Unit: billion yen)

LSV 2030 LINTEC SUSTAINABILITY VISION Stage 2	FY2024/3	FY2027/3	Change (% change)
Net sales	276.3	**315.0**	+38.7 (+14%)
Operating income	10.6	**25.5**	+14.9 (+141%)
Profit attributable to owners of parent	5.2	**18.0**	+12.8 (+246%)
Operating profit margin	3.8%	**8% or more**	-
Return on equity (ROE)	2.3%	**8% or more**	-

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Cash allocation (FY2024-FY2026 cumulative)

- **Make effective use of cash to strengthen our financial base and invest in production facilities and R&D to raise our value as an enterprise**

Cash flow during the Stage 2 period
(Operating income + depreciation + amortization of goodwill)
Approx. 130.0 billion yen

External financing

Growth investments

Capital investment etc. **Approx. 60.0 billion yen**	• Multilayer ceramic capacitor-related tape coating facilities • Semiconductor-related adhesive tape coating facilities • Release paper coating facilities • Environment-related investments • DX-related investments
R&D investment **Approx. 32.0 billion yen**	• Development of new tapes, equipment, and original processes related to semiconductor packaging technology • Establishment of system for mass production of CNT pellicles for EUV lithography machines • Development of environmentally friendly products
M&A and other flexible investments	• Expansion into new countries/regions, new markets, and new fields

Shareholder returns

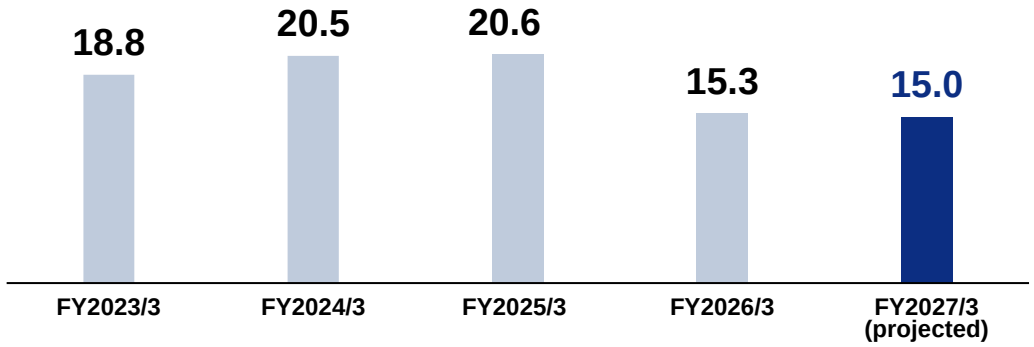
- **In principle, no decrease in dividends through FY2027/3, the final fiscal year of Stage 2, while paying dividends targeting a payout ratio of 40% or higher or DOE of 3%**
- **Flexible share buybacks**

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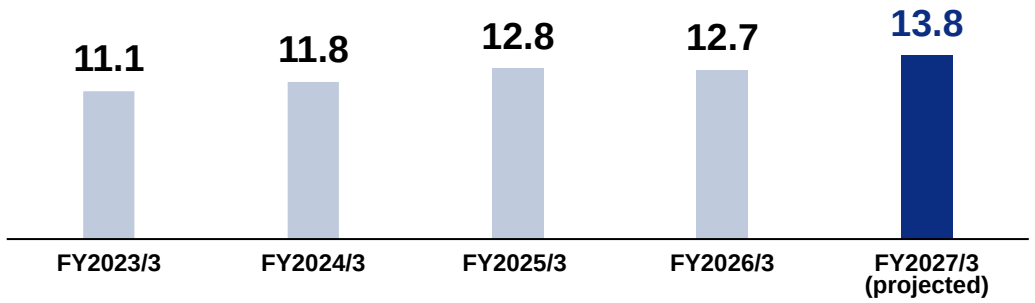
Capital expenditures / Depreciation / Amortization of goodwill / R&D expenses

Actual Projected (Unit: billion yen)

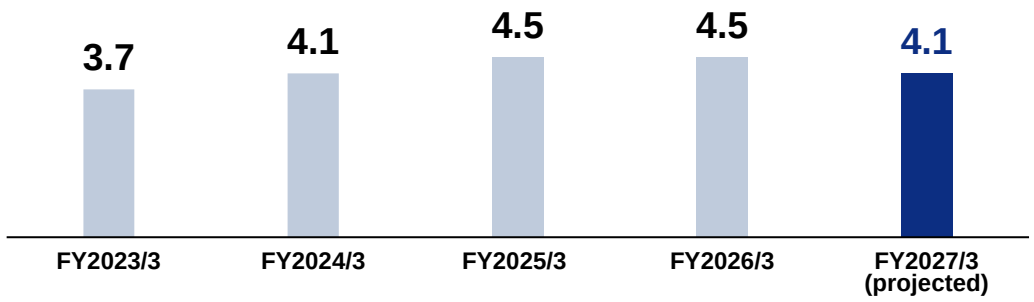
Capital expenditures



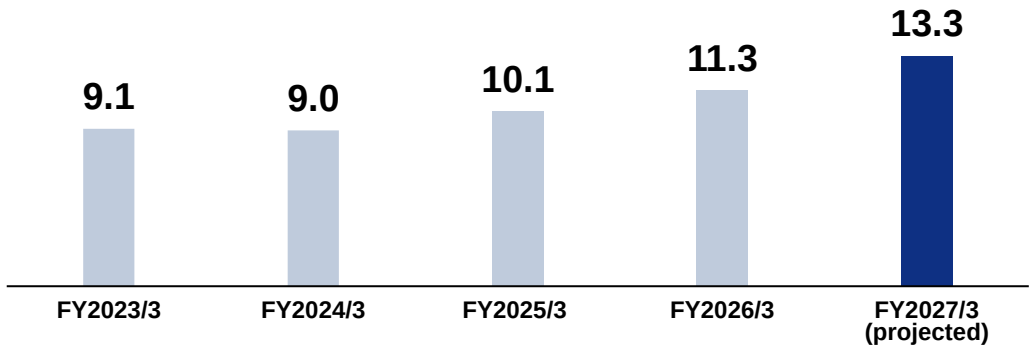
Depreciation



Amortization of goodwill



R&D expenses



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